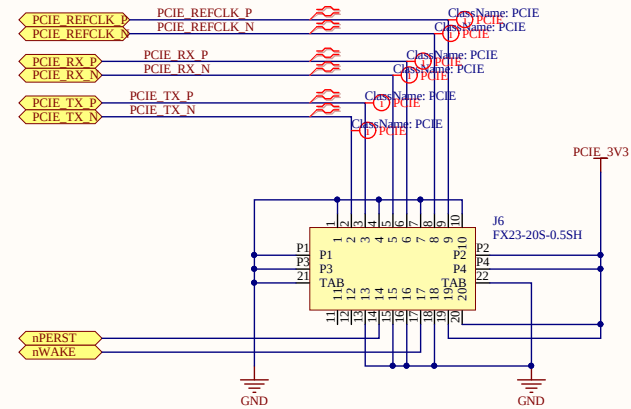
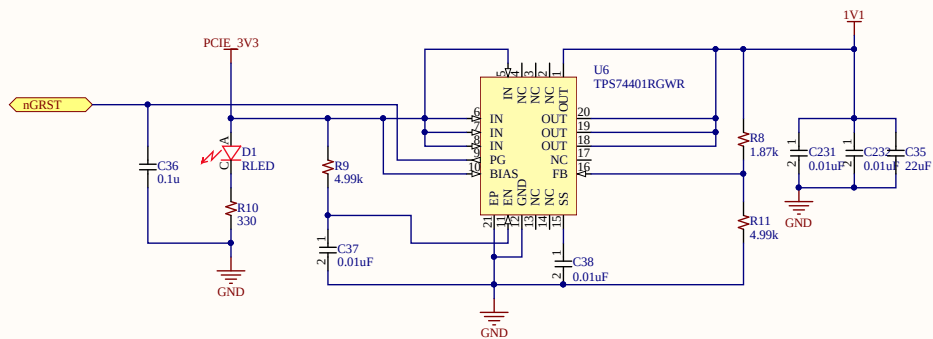
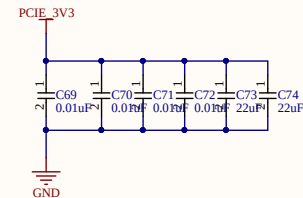
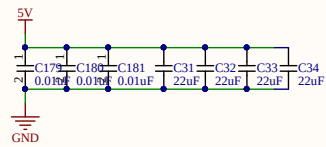
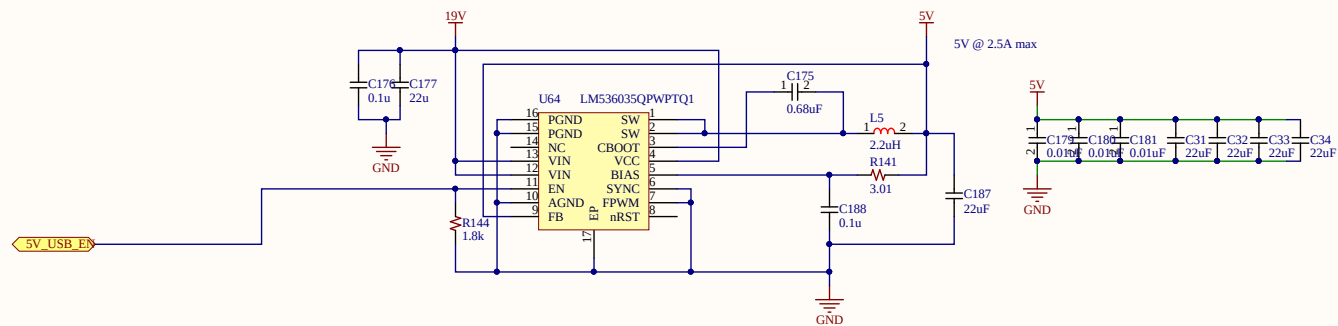
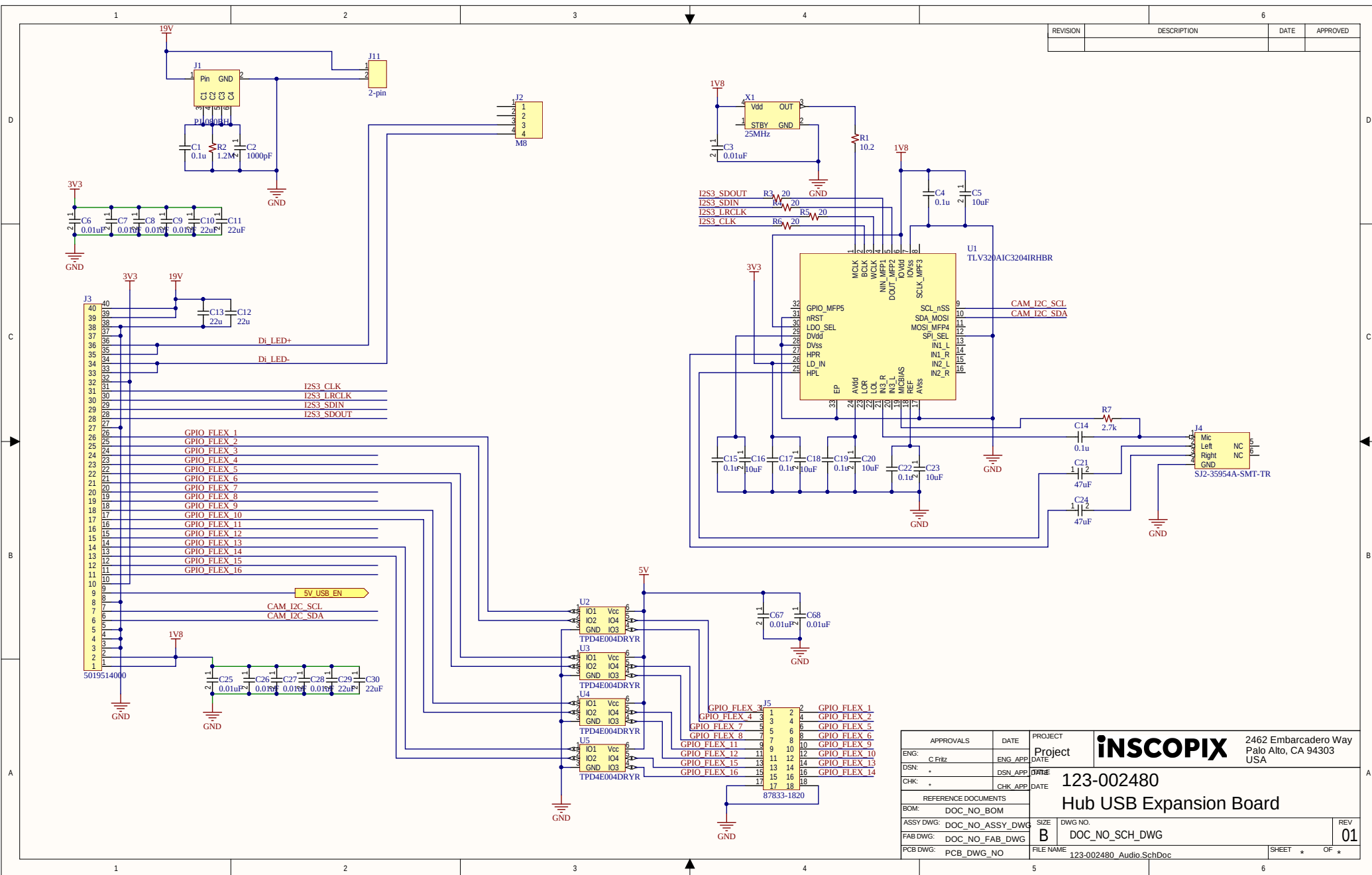
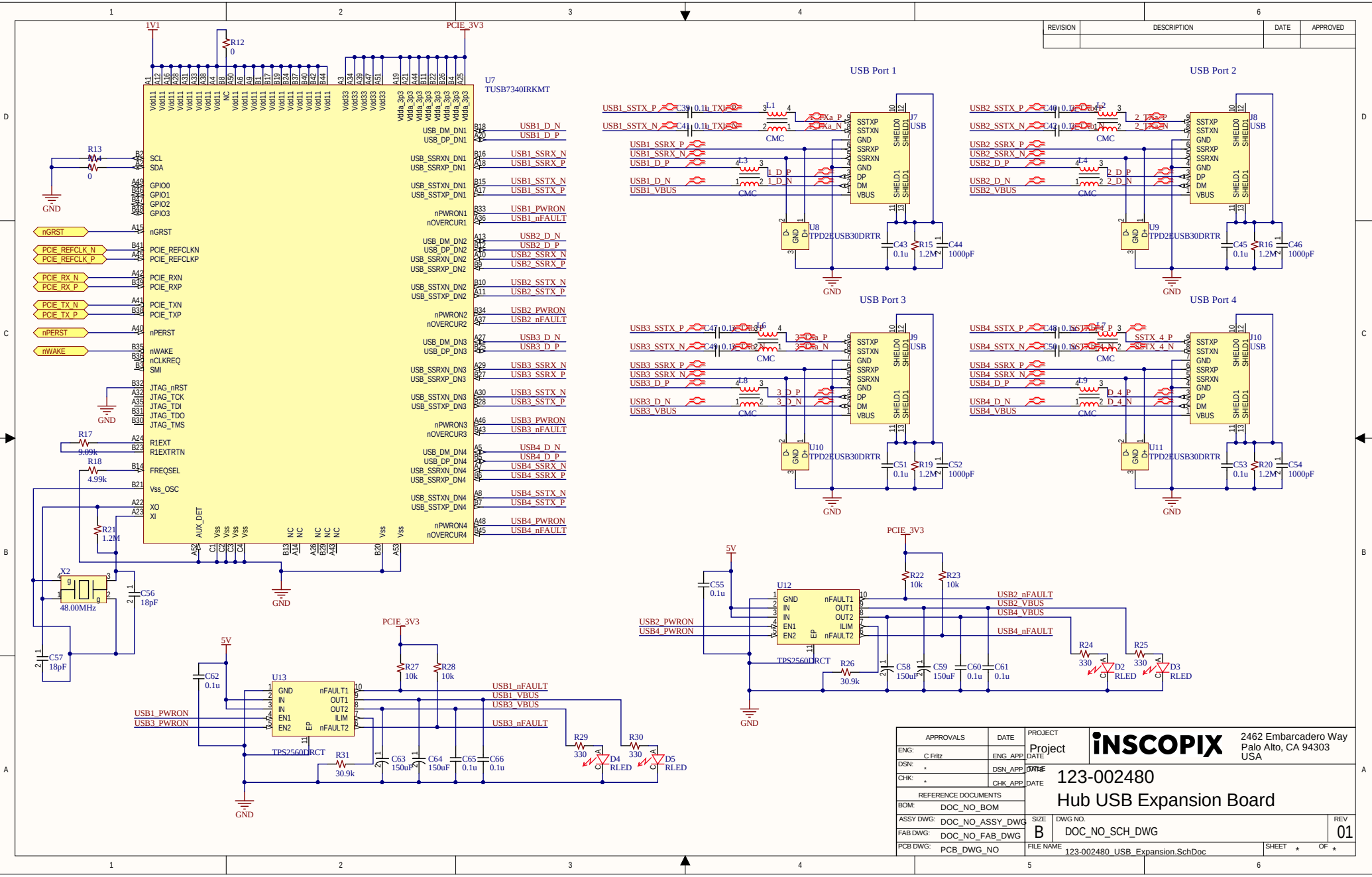
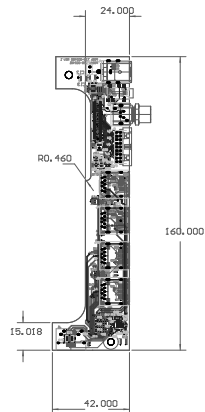




Title		
Power & PCIe		
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NOTES:	
1	SPECIFICATIONS
1.1	FABRICATE PER ANSI/IPC-ML-950 CLASS 2 (GENERAL INDUSTRY)
1.2	INSCOPIX MUST BE ADVISED IN WRITING IN ADVANCE OF MANUFACTURING OF ANY CHANGES, REVISIONS, OR CORRECTIONS MADE OR RECOMMENDATIONS TO ENSURE CONFORMANCE TO INSCOPIX STANDARDS
1.3	THIS DRAWING IS TO BE USED IN CONJUNCTION WITH THE PROVIDED GERBER AND DRILL DATA WHEN APPLICABLE
1.4	ALL NOTES ARE UNLESS OTHERWISE SPECIFIED
2	MATERIAL
2.1	NEM A GRADE FR-4/EPOXY CLASS, FOIL LAMINATION STRUCTURE FOR CORE AND COPPER THICKNESS; TYPE GFN, IAW MIL-P-13949/4.11
2.2	SEE CROSS SECTION FOR CU FOIL WEIGHTS
2.3	LAMINATE AND MOLDED PREPREG DIELECTRIC CONSTANTS SHALL BE 4.3 +/- 0.3 AT 1.0 MHZ
2.4	COLOR TO BE OPAQUE
2.5	TG TO BE 170 C OR BETTER
3	SOLDERMASK
3.1	SOLDER MASK PER IPC-SM-840 CLASS 2 BOTH SIDES WITH (GREEN COLOR) LIQUID PHOTO IMAGEABLE SOLDERMASK
3.2	SOLDERMASK OVER BARE COPPER
4	DRILLING
4.1	ALL HOLES FINISHED SIZE AS SHOWN
4.2	ALL HOLES TO BE +/- 0.08 MM FROM TRUE POSITION UNLESS OTHERWISE SPECIFIED
4.3	ALL HOLE DIAMETERS TO BE +/- 0.08 MM UNLESS OTHERWISE SPECIFIED
4.4	AN NC DRILL FILE HAS BEEN SUPPLIED - SEE HOLE SIZE TABLE
5	FINISH
	PLATE HOLES THRU WITH COPPER 0.025 MM MIN TO 0.05 MM MAX THICKNESS DRILL SIZE DIMENSIONS APPLY AFTER PLATING
	FINAL FINISH: ELECTROLESS NIKKEL IMMERSION GOLD (ENIG), 100 MICRO INCHES NICKEL MINIMUM, 2 TO 8 MICRO INCHES GOLD, NO METALIC CO-DEPOSITS
6	SILKSCREEN
6.1	SILKSCREEN USING WHITE NON-CONDUCTIVE EPOXY OR EQUIVALENT (BOTH SIDES)
6.2	NO SILKSCREEN ALLOWED ON EXPOSED LANDS OR IN HOLES
6.3	REGISTRATION TO BE +/- 0.1 MM AND MUST PASS PEEL TEST
7	ELECTRICAL TEST
7.1	ALL BOARDS SHALL BE 100% ELECTRICALLY TESTED BY FABRICATOR FOR TRACE CONTINUITY AND PROOF AGAINST TRACE SHORTS.
7.2	APPLY TEST STAMP IN NON-LEGEND AREA A ON SOLDER SIDE OF PCB
7.3	CERTIFICATION REQUIRED
8	CLEANLINESS
8.1	BOARDS SHALL BE FREE OF FIBER GLASS DUST OR ANY OTHER FOREIGN MATERIAL
8.2	FINISHED BOARDS MUST CONFORM TO 0.01 MG/N MAX NaCl IONIC CONTAMINATION AS MEASURED BY THE OMEGA METER 600SMD
9	PACKAGING
91	THERE SHALL BE A MAXIMUM OF 25 UNITS PER PACKAGE INDIVIDUALLY WRAPPED AND SHIPPED IN CARDBOARD CARTONS WITH SUFFICIENT SURROUNDING MATERIAL TO PREVENT DAMAGE
10	BOW AND TWIST
10.1	BOW AND TWIST TO BE 0.007 IN/IN OR 0.090 MAX ACCORDING TO IPC-A-600D
11	INSPECTION
11.1	AUTOMATIC OPTICAL INSPECTION OF ALL LAYERS REQUIRED
11.2	A MICROSECTION EXHIBITING ALL LAYERS IS REQUIRED WITH EACH LOT/DATE CODE
11.3	A CERTIFICATION OF COMPLIANCE IS REQUIRED WITH EACH SHIPMENT
12	UL RATING
12.1	FINISHED BOARD INCLUDING ANY SOLDERMASK OR LEGENDS SHALL HAVE A UL FLAMMABILITY RATING OF 94V-D
12.2	DATE CODE AND MANUFACTURERS UL SYMBOL/TYPE SHALL BE PERMANENTLY MARKED OR ETCHED SOMEWHERE ON THE BOARD
13	IMPEDANCE
13.1	ANY DEVIATION FROM THE STACKUP MUST HAVE INSCOPIX APPROVAL

